

Title (en)
STRUCTURAL LEAD FRAME

Title (de)
STRUKTURELLER LEITERRAHMEN

Title (fr)
GRILLE DE CONNEXION STRUCTURELLE

Publication
EP 4100975 A4 20240807 (EN)

Application
EP 21741869 A 20210113

Priority
• US 202062969408 P 20200203
• US 2021013238 W 20210113

Abstract (en)
[origin: US2021241977A1] Provided is an improved electronic component package. The electronic component package comprises a multiplicity of electronic components wherein each electronic component comprises a first external termination and a second external termination. The electronic component package also includes a structural lead frame comprising multiple leads wherein each lead is mounted to at least one first external termination and the structural lead frame comprises at least one break away feature between adjacent leads.

IPC 8 full level
H01G 2/06 (2006.01); **H01G 4/38** (2006.01); **H01L 23/488** (2006.01); **H01L 23/498** (2006.01); **H05K 1/18** (2006.01); **H05K 7/14** (2006.01)

CPC (source: EP US)
H01G 2/04 (2013.01 - US); **H01G 2/06** (2013.01 - EP); **H01G 2/08** (2013.01 - EP US); **H01G 2/10** (2013.01 - US); **H01G 4/224** (2013.01 - EP); **H01G 4/228** (2013.01 - EP); **H01G 4/232** (2013.01 - EP); **H01G 4/30** (2013.01 - EP US); **H01G 4/38** (2013.01 - EP US); **H01G 13/00** (2013.01 - US); **H05K 1/0204** (2013.01 - EP); **H05K 1/0272** (2013.01 - US); **H05K 1/145** (2013.01 - EP US); **H05K 1/18** (2013.01 - EP US); **H05K 1/181** (2013.01 - US); **H05K 3/328** (2013.01 - US); **H01G 2/04** (2013.01 - EP); **H01G 4/12** (2013.01 - EP); **H01G 4/258** (2013.01 - EP); **H01G 13/006** (2013.01 - EP); **H01L 25/072** (2013.01 - US); **H01L 29/1608** (2013.01 - US); **H01L 29/2003** (2013.01 - US); **H05K 1/0259** (2013.01 - EP); **H05K 3/328** (2013.01 - EP); **H05K 2201/10015** (2013.01 - EP US); **H05K 2201/10166** (2013.01 - EP US); **H05K 2201/10272** (2013.01 - EP); **H05K 2201/10424** (2013.01 - US); **H05K 2201/10454** (2013.01 - EP); **H05K 2201/10522** (2013.01 - EP); **H05K 2201/10537** (2013.01 - EP); **H05K 2201/10545** (2013.01 - US)

Citation (search report)
• [X] KR 20190121156 A 20191025 - SAMSUNG ELECTRO MECH [KR]
• [A] US 2009284897 A1 20091119 - ITAMURA HIROTO [JP]
• [A] US 8304321 B2 20121106 - SATO MOTOHIKO [JP], et al
• [A] EP 0259630 A1 19880316 - SIEMENS AG [DE]
• See also references of WO 2021146284A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
US 11923151 B2 20240305; **US 2021241977 A1 20210805**; CN 114787950 A 20220722; EP 4100975 A1 20221214; EP 4100975 A4 20240807; WO 2021146284 A1 20210722; WO 2021146284 A8 20220609

DOCDB simple family (application)
US 202117148038 A 20210113; CN 202180006941 A 20210113; EP 21741869 A 20210113; US 2021013238 W 20210113